

# 2A, 200V-1000V High Efficient Surface Mount Rectifiers

#### **FEATURES**

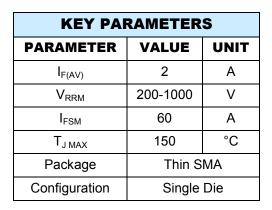
- Glass passivated junction chip
- Ideal for automated placement
- Low power loss, high efficiency
- · Fast switching for high efficiency
- Low profile package
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- Freewheeling application
- Switching mode converters and inverters, computer and telecommunication.

#### **MECHANICAL DATA**

- · Case: Thin SMA
- Molding compound meets UL 94V-0 flammability rating
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Pure tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.029 g (approximately)











Thin SMA

ABSOLUTE MAXIMUM RAT			l i i					T
PARAMETER	SYM	BOL	HS2DAL	HS2GAL	HS2JAL	HS2KAL	HS2MAL	UNIT
Marking code on the device			HS2DAL	HS2GAL	HS2JAL	HS2KAL	HS2MAL	
Repetitive peak reverse voltage		RM	200	400	600	800	1000	V
Reverse voltage, total rms value	e V <sub>R(F</sub>	RMS)	140	280	420	560	700	V
Forward current	I <sub>F(</sub> ,				2			Α
Surge peak forward current, single half sine-wave	· .				60			А
superimposed on rated load per diode	I <sub>FS</sub>	SM			120			А
Junction temperature	Т	- J	-55 to +150			°C		
Storage temperature	Ts	<sub>STG</sub> -55 to +150			°C			

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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	R <sub>OJL</sub>	17	°C/W	
Junction-to-ambient thermal resistance	R <sub>OJA</sub>	53	°C/W	
Junction-to-case thermal resistance	R <sub>eJC</sub>	21	°C/W	

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
		I <sub>F</sub> = 1.0A, T <sub>J</sub> = 25°C		0.81	-	V
	LICODAL	I <sub>F</sub> = 2.0A, T <sub>J</sub> = 25°C		0.87	1.00	V
	HS2DAL	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C		0.67	-	V
		I <sub>F</sub> = 2.0A, T <sub>J</sub> = 125°C		0.74	0.82	V
	HESCAL	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 25°C	V <sub>F</sub>	0.90	-	V
		I <sub>F</sub> = 2.0A, T <sub>J</sub> = 25°C		0.99	1.30	V
	HS2GAL	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C		0.76	-	V
		I <sub>F</sub> = 2.0A, T <sub>J</sub> = 125°C		0.86	0.96	V
Forward voltage per diode <sup>(1)</sup>		I <sub>F</sub> = 1.0A, T <sub>J</sub> = 25°C		1.00	-	V
	1100141	I <sub>F</sub> = 2.0A, T <sub>J</sub> = 25°C		1.10	1.70	V
	HS2JAL	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C		0.80	-	V
		I <sub>F</sub> = 2.0A, T <sub>J</sub> = 125°C		0.92	1.10	V
	HS2KAL HS2MAL	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 25°C		1.30	-	V
		I <sub>F</sub> = 2.0A, T <sub>J</sub> = 25°C		1.48	1.70	V
		I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C		0.94	-	V
		I <sub>F</sub> = 2.0A, T <sub>J</sub> = 125°C		1.11	1.23	V
Reverse current @ rated V <sub>R</sub> per diode <sup>(2)</sup>		T <sub>J</sub> = 25°C		-	1	μA
		T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	80	μA
	HS2DAL HS2GAL	1 0 5 1 1 0 1		-	50	ns
Reverse recovery time	HS2JAL HS2KAL HS2MAL	- I <sub>F</sub> =0.5A,I <sub>R</sub> =1.0A, Irr=0.25A	t <sub>rr</sub>	-	75	ns
	HS2DAL		CJ	32	-	pF
	HS2GAL			25	-	pF
Junction capacitance per diode	HS2JAL	1 MHz, V <sub>R</sub> =4.0V		17	-	pF
	HS2KAL HS2MAL			12	-	pF

#### Notes:

- (1) Pulse test with PW=0.3 ms
- (2) Pulse test with PW=30 ms



## Taiwan Semiconductor

ORDERING INFORMATION				
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING		
HS2xAL M3G	Thin SMA	3,500 / 7" reel		
HS2xAL M2G	Thin SMA	14,000 / 13" reel		

#### Notes:

(1) "x" defines voltage from 200V(HS2DAL) to 1000V(HS2MAL)



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

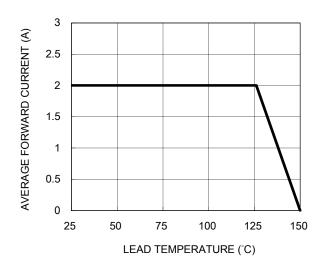


Fig.3 Typical Reverse Characteristics

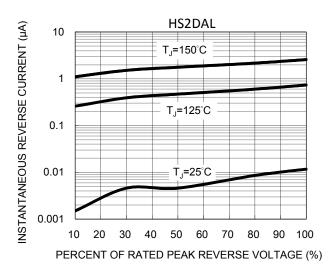


Fig.5 Typical Reverse Characteristics

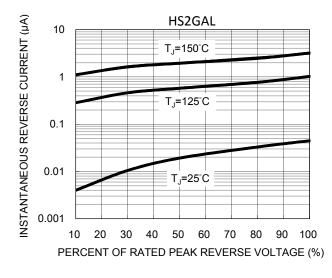


Fig.2 Typical Junction Capacitance

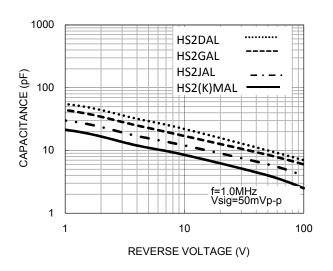


Fig.4 Typical Forward Characteristics

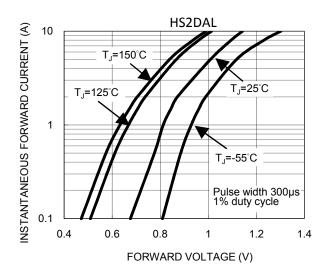


Fig.6 Typical Forward Characteristics

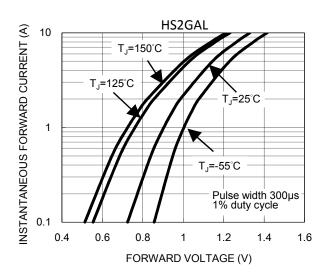
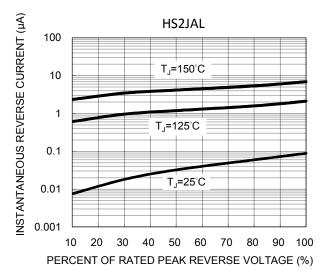




Fig.7 Typical Reverse Characteristics



**Fig.9 Typical Reverse Characteristics** 

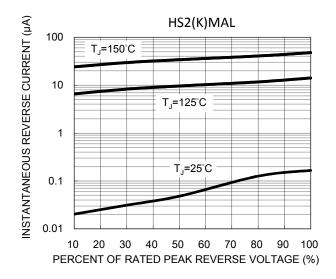


Fig.8 Typical Forward Characteristics

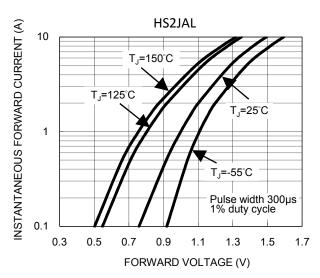


Fig.10 Typical Forward Characteristics

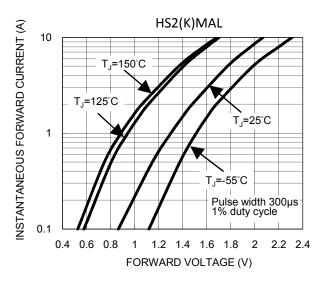
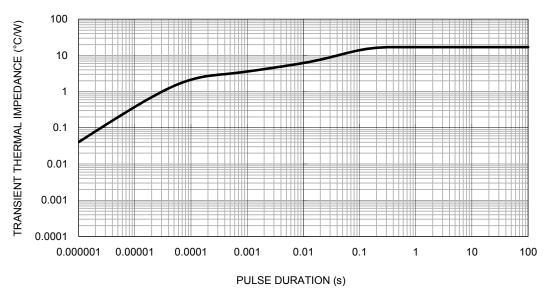


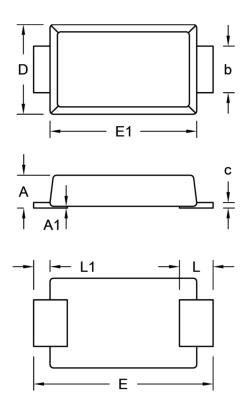
Fig.11 Typical Transient Thermal Impedance





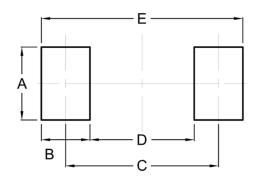
### **PACKAGE OUTLINE DIMENSIONS**

Thin SMA



DIM.	Unit	(mm)	Unit (inch)		
Dilvi.	Min.	Max.	Min.	Max.	
Α	0.90	1.00	0.035	0.039	
A1	0.00	0.10	0.000	0.004	
b	1.25	1.45	0.049	0.057	
С	0.10	0.22	0.004	0.009	
D	2.50	2.70	0.098	0.106	
Е	5.05	5.35	0.199	0.211	
E1	4.15	4.35	0.163	0.171	
L	0.75	1.20	0.030	0.047	
L1	0.30	0.60	0.012	0.024	

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

### **MARKING DIAGRAM**



P/N = Marking Code YW = Date Code F = Factory Code

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